

AMPMODU | AMPMODU HE 13/HE 14

TE Internal #: 281695-4

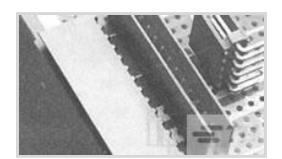
PCB Mount Header, Vertical, Wire-to-Board, 4 Position, .1 in [2.54 mm] Centerline, Partially Shrouded, Tin, Through Hole - Solder,

AMPMODU HE 13/HE 14

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Connectors > PCB Connectors > PCB Headers & Receptacles > HE13/HE14 TH Headers, SRST



Connector System: Wire-to-Board

Number of Positions: 4
Number of Rows: 1

Centerline (Pitch): 2.54 mm [.1 in]
PCB Mount Orientation: Vertical

All HE13/HE14 TH Headers, SRST (21)

Features

Product Type Features

Connector System	Wire-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header

Configuration Features

Connector Contact Load Condition	Fully Loaded
Number of Positions	4
Number of Rows	1
PCB Mount Orientation	Vertical

Electrical Characteristics

Insulation Resistance	1000 ΜΩ
Dielectric Withstanding Voltage (Max)	500 V

Body Features

Contact Features



Contact Mating Area Length	7 mm
Mating Square Post Dimension	.64 mm[.025 in]
Contact Mating Area Plating Material Thickness	.8 μm[31 μin]
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Matte
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.63 mm[.025 in]
Termination Post & Tail Length	2.9 mm
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Alignment Type Mating Retention	Polarization With
Mating Retention	With
Mating Retention Panel Mount Feature	Without
Mating Retention Panel Mount Feature Connector Mounting Type	With Without Board Mount
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment	With Without Board Mount With
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention	With Without Board Mount With
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features	Without Board Mount With With
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material	Without Board Mount With With High Temperature Thermoplastic
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch)	Without Board Mount With With High Temperature Thermoplastic
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Usage Conditions	With Without Board Mount With With High Temperature Thermoplastic 2.54 mm[.1 in]
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Usage Conditions Operating Temperature Range	With Without Board Mount With With High Temperature Thermoplastic 2.54 mm[.1 in]
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Usage Conditions Operating Temperature Range Operation/Application	With Without Board Mount With With Without High Temperature Thermoplastic 2.54 mm[.1 in]
Mating Retention Panel Mount Feature Connector Mounting Type Mating Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Usage Conditions Operating Temperature Range Operation/Application Circuit Application	With Without Board Mount With With Without High Temperature Thermoplastic 2.54 mm[.1 in]



Packaging Features

Packaging Quantity	2000
Packaging Type	Bag

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts











Also in the Series | AMPMODU HE 13/HE 14



Customers Also Bought



Documents

Product Drawings

HEADER HE14 STRAIGHT 4 P

English

CAD Files

Customer View Model

ENG_CVM_CVM_281695-4_G.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_281695-4_G.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_281695-4_G.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

French

Product Environmental Compliance

MD_281695-4_06122014118_dmtec

PCB Mount Header, Vertical, Wire-to-Board, 4 Position, .1 in [2.54 mm] Centerline, Partially Shrouded, Tin, Through Hole - Solder, AMPMODU HE 13/HE 14



English

MD_281695-4_06122014118_dmtec

English